

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Test methods for electrical materials, printed board and other interconnection structures and assemblies –**

**Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards**

**Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –**

**Partie 5-503: Méthode d'essai générale pour les matériaux et les assemblages – Essais des filaments anodiques conducteurs (CAF) des cartes à circuits**



## THIS PUBLICATION IS COPYRIGHT PROTECTED

Copyright © 2017 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

Droits de reproduction réservés. Sauf indication contraire, aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'IEC ou du Comité national de l'IEC du pays du demandeur. Si vous avez des questions sur le copyright de l'IEC ou si vous désirez obtenir des droits supplémentaires sur cette publication, utilisez les coordonnées ci-après ou contactez le Comité national de l'IEC de votre pays de résidence.

IEC Central Office  
3, rue de Varembe  
CH-1211 Geneva 20  
Switzerland

Tel.: +41 22 919 02 11  
[info@iec.ch](mailto:info@iec.ch)  
[www.iec.ch](http://www.iec.ch)

### About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

### About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigendum or an amendment might have been published.

#### IEC publications search - [webstore.iec.ch/advsearchform](http://webstore.iec.ch/advsearchform)

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee,...). It also gives information on projects, replaced and withdrawn publications.

#### IEC Just Published - [webstore.iec.ch/justpublished](http://webstore.iec.ch/justpublished)

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and once a month by email.

#### IEC Customer Service Centre - [webstore.iec.ch/csc](http://webstore.iec.ch/csc)

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: [sales@iec.ch](mailto:sales@iec.ch).

#### Electropedia - [www.electropedia.org](http://www.electropedia.org)

The world's leading online dictionary on electrotechnology, containing more than 22 000 terminological entries in English and French, with equivalent terms in 16 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

#### IEC Glossary - [std.iec.ch/glossary](http://std.iec.ch/glossary)

67 000 electrotechnical terminology entries in English and French extracted from the Terms and Definitions clause of IEC publications issued since 2002. Some entries have been collected from earlier publications of IEC TC 37, 77, 86 and CISPR.

### A propos de l'IEC

La Commission Electrotechnique Internationale (IEC) est la première organisation mondiale qui élabore et publie des Normes internationales pour tout ce qui a trait à l'électricité, à l'électronique et aux technologies apparentées.

### A propos des publications IEC

Le contenu technique des publications IEC est constamment revu. Veuillez vous assurer que vous possédez l'édition la plus récente, un corrigendum ou amendement peut avoir été publié.

#### Recherche de publications IEC - [webstore.iec.ch/advsearchform](http://webstore.iec.ch/advsearchform)

La recherche avancée permet de trouver des publications IEC en utilisant différents critères (numéro de référence, texte, comité d'études,...). Elle donne aussi des informations sur les projets et les publications remplacées ou retirées.

#### IEC Just Published - [webstore.iec.ch/justpublished](http://webstore.iec.ch/justpublished)

Restez informé sur les nouvelles publications IEC. Just Published détaille les nouvelles publications parues. Disponible en ligne et une fois par mois par email.

#### Service Clients - [webstore.iec.ch/csc](http://webstore.iec.ch/csc)

Si vous désirez nous donner des commentaires sur cette publication ou si vous avez des questions contactez-nous: [sales@iec.ch](mailto:sales@iec.ch).

#### Electropedia - [www.electropedia.org](http://www.electropedia.org)

Le premier dictionnaire d'électrotechnologie en ligne au monde, avec plus de 22 000 articles terminologiques en anglais et en français, ainsi que les termes équivalents dans 16 langues additionnelles. Egalement appelé Vocabulaire Electrotechnique International (IEV) en ligne.

#### Glossaire IEC - [std.iec.ch/glossary](http://std.iec.ch/glossary)

67 000 entrées terminologiques électrotechniques, en anglais et en français, extraites des articles Termes et Définitions des publications IEC parues depuis 2002. Plus certaines entrées antérieures extraites des publications des CE 37, 77, 86 et CISPR de l'IEC.

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Test methods for electrical materials, printed board and other interconnection structures and assemblies –  
Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards**

**Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –  
Partie 5-503: Méthode d'essai générale pour les matériaux et les assemblages – Essais des filaments anodiques conducteurs (CAF) des cartes à circuits**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

COMMISSION  
ELECTROTECHNIQUE  
INTERNATIONALE

ICS 31.180

ISBN 978-2-8322-7362-3

**Warning! Make sure that you obtained this publication from an authorized distributor.  
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.**

## CONTENTS

FOREWORD.....	4
1 Scope.....	6
2 Normative references .....	6
3 Terms and definitions .....	6
4 Testing condition .....	7
4.1 Standard condition .....	7
4.2 Judgment state .....	8
5 Specimen .....	8
5.1 Outline of CAF test vehicle design .....	8
5.1.1 Evaluation design for the glass cloth direction .....	8
5.1.2 Design between plated through hole (PTH).....	9
5.2 CAF test board.....	10
5.2.1 Example A.....	10
5.2.2 Example B.....	11
5.3 Number of specimens .....	13
6 Equipment/Apparatus or material.....	13
6.1 Environmental test chamber.....	13
6.2 Measuring equipment.....	13
6.3 Power supply .....	13
6.4 Current limiting resistors .....	14
6.5 Connecting wire .....	14
6.6 Other dedicated fixtures.....	14
7 Resistance measurement method .....	14
7.1 Manual insulation resistance measurement method .....	14
7.2 Automatic insulation resistance measurement method .....	15
8 Test method .....	16
8.1 Test method selection .....	16
8.2 Steady-state temperature and humidity test .....	16
8.2.1 Object.....	16
8.2.2 Test condition.....	16
8.3 Temperature and humidity (12 h + 12 h) cycle test.....	16
8.3.1 Object.....	16
8.3.2 Test condition.....	17
8.3.3 Number of cycles of the test .....	17
8.4 Temperature and humidity cyclic test with and without low temperature exposure.....	17
8.4.1 Object.....	17
8.4.2 Test condition.....	17
8.5 Steady-state high temperature and high humidity (unsaturated pressurized vapour) test .....	17
8.5.1 Object.....	17
8.5.2 Test condition .....	18
9 Procedure.....	18
9.1 Test specimen preparation.....	18
9.1.1 General .....	18
9.1.2 Sample identification .....	18

9.1.3	Prescreen for opens and shorts .....	18
9.1.4	Cleaning .....	19
9.1.5	Connecting wire .....	19
9.1.6	Cleaning after attachment .....	19
9.1.7	Dry .....	19
9.2	Precondition .....	19
9.3	Test procedure .....	19
9.3.1	Setting of the specimen .....	19
9.3.2	Test voltage and measuring voltage .....	19
9.3.3	Temperature and humidity condition at the start time of the test .....	20
9.3.4	Measurement .....	20
9.3.5	Procedure in test interruption .....	21
9.3.6	End of test .....	21
9.4	Visual inspection .....	21
9.4.1	General .....	21
9.4.2	Shape of electrochemical migration .....	21
Annex A (informative)	Forms of electrochemical migration .....	22
A.1	Example of dendrite-shaped migration .....	22
A.2	CAF (Example of migration along the glass fibre) .....	22
Bibliography	.....	23
Figure 1	– Schematic of in-line test comb, with possible failure site .....	8
Figure 2	– Schematic of staggered test comb, with possible failure site .....	9
Figure 3	– Manhattan distance .....	9
Figure 4	– Schematic section of via pair with bias .....	10
Figure 5	– Example of inner layer via pads and layer patterns .....	10
Figure 6	– Example of no inner layer vias and layer patterns .....	10
Figure 7	– Insulation evaluation pattern for through-holes and via holes .....	11
Figure 8	– Layouts of the two versions of the CAF test boards .....	12
Figure 9	– Measurement with insulation resistance meter .....	15
Figure 10	– Temperature and humidity in a test .....	20
Figure A.1	– Example of dendrite-shaped migration generated on the board surface .....	22
Figure A.2	– Example of CAF .....	22
Table 1	– Dimension of insulation evaluation pattern for through-holes .....	11
Table 2	– Test structures A1 through A4 design rules .....	12
Table 3	– Test structures B1 through B4 design rules .....	13
Table 4	– Test condition .....	16
Table 5	– Number of cycles of the test .....	17
Table 6	– Test condition .....	17
Table 7	– Test condition (IEC 60068-2-66) .....	18

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD  
AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 5-503: General test method for materials and assemblies –  
Conductive anodic filaments (CAF) testing of circuit boards**

## FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization, comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, issue to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 61189-5-503 been prepared by IEC technical committee 91: Electronics assembly technology.

This bilingual version (2019-09) corresponds to the monolingual English version, published in 2017-05.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1433/FDIS	91/1443/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

The French version of this standard has not been voted upon.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

**IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.**

# TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

## Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards

### 1 Scope

This part of IEC 61189 specifies the conductive anodic filament (hereafter referred to as CAF) and specifies not only the steady-state temperature and humidity test, but also a temperature-humidity cyclic test and an unsaturated pressurized vapour test (HAST).

### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1:2013, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-30, *Environmental testing – Part 2-30: Tests – Test Db: Damp heat, cyclic (12 h + 12 h cycle)*

IEC 60068-2-38, *Environmental testing – Part 2-38: Tests – Test Z/AD: Composite temperature/humidity cyclic test*

IEC 60068-2-66, *Environmental testing – Part 2: Test methods – Test Cx: Damp heat, steady state (unsaturated pressurized vapour)*

IEC 60068-2-67, *Environmental testing – Part 2: Tests – Test Cy: Damp heat, steady state, accelerated test primarily intended for components*

IEC 60068-2-78, *Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state*

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IPC-TM-650 No.2.6.14.1, *Electrochemical Migration Resistance Test [viewed 2017-01-31]. Available at: [https://www.ipc.org/TM/2-6\\_2-6-14-1.pdf](https://www.ipc.org/TM/2-6_2-6-14-1.pdf)*

IPC-TM-650 No.2.6.25, *Conductive Anodic Filament (CAF) Resistance Test: X-Y Axis [viewed 2017-01-31]. Available at: [https://www.ipc.org/4.0\\_Knowledge/4.1\\_Standards/test/2-6-25.pdf](https://www.ipc.org/4.0_Knowledge/4.1_Standards/test/2-6-25.pdf)*

### 3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 and IEC 60068-1 as well as the following apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses: